

Product Change Notification PCN97002

Additional Product Assembly Qualification of A.S.E. Taiwan

Subject: Additional Product Assembly Qualification of A.S.E. Taiwan

Products Affected: All BGA Packages

Change Description: Xilinx previously announced ([PCN96005](#) issued on 28 June 1996) the qualification of the A.S.E. facility in Kaohsiung, Taiwan for the assembly of PLCC and PQFP packages. This PCN extends that qualification for Ball Grid Assemblies (BGAs).

Product Change: There are no changes in electrical or mechanical specifications. The package piece parts (mold compound, leadframe, etc.) as well as the manufacturing processes are totally compatible with the BGA products that Xilinx currently supplies from other assembly facilities.

Reason For Change: To provide additional assembly capacity. This addition is being made in support of our continuous effort towards improving total customer satisfaction.

Qualification Data: Xilinx performed a full on-site quality and technical audit of the A.S.E. Kaohsiung facility in November 1995 and a follow-up audit in April 1996, and verified A.S.E.'s conformance to Xilinx' and ISO-9000 requirements. Reliability Qualification Testing was performed on BGA products assembled in this facility, and [data is attached](#).

Traceability: For traceability purposes, the 3rd line of the product top mark will show a "T" prefix.

Immediate response to this notification is not required. For any questions regarding this PCN you may contact Xilinx via email at "pcn@xilinx.com", or by FAX at (408) 559-1368.